Chip Design Marketing and Lead Generation Programs Connect You with Real Buyers in the Advanced IC Design Market

Influence the largest, most qualified community of design engineers and engineering managers working on advanced SoC designs

Chip Design’s in-depth magazine, convenient email newsletters and content-rich websites are seen by more than 120,000 engineering and management professionals in 101 countries each month—more than any other Chip Design-focused media provider delivers. These influential professionals rely on Chip Design for SoC design, EDA, ASICs, IP, FPGAs, RF, and Low Power design articles and product information.

Chip Design ensures our content and your message reach buyers worldwide in the formats they prefer, including:

- **www.ChipDesignMag.com**: Purchase influencers research suppliers and products online using the Chip Design portal’s informative articles, video library, news, research, white papers, and Featured Solutions guide.

- **Premium Content Channel**: System Design Engineering. Our Industry leading editors create valuable content featuring our sponsors and their technology and deliver it to their target audience.

- **Magazine**: Our qualified audience of buyers is the largest and most diverse served by any Chip Design-focused magazine. They rely on our leading-edge and strategic articles and commentary to help make EDA; ASICs, FPGAs and PLD Design; IP and test equipment/development tools technology decisions.

- **Email Newsletters**: Design engineers and engineering managers working on advanced SoC designs stay informed by reading Chip Designer and IP Designer & Integrator for important industry news, product information, research, videos and more.

- **Events**: Semiconductor design and manufacturing industry leaders gather each year at The Confab to connect, collaborate and create the future. Executives and Engineers involved in the Multicore and IoT industries gather each year at the Multicore DevCon and Internet of Things Developers Conference.

Chip Design’s authoritative content attracts more influential buyers focused on creating the latest generations of ASICs, structured ASIC, ASSPs, FPGAs, memory cored and SoC devices.

Our advertising, sponsorship, marketing survey/lead generation, editorial sponsorships and content syndication options are among the most efficient ways to increase purchase consideration for your products among these buyers by:

- Increasing your brand visibility,
- Attracting targeted sales leads, and
- Promoting your thought leadership and expertise through editorial sponsorship or syndication of your content.

We look forward to the opportunity to work with you in 2015.
Editorial Team and Focus

Informing Chip and SoC design decision makers with unparalleled technology and business insights

PETE SINGER, Editorial Director & Associate Publisher
Pete oversees the editorial operations of Chip Design, Solid State Technology and The ConFab. He has been involved in technical journalism for more than 30 years and has written over 150 articles on all aspects of semiconductor manufacturing and design industries. Pete holds a degree in Electrical Engineering from the University of Illinois, Champaign-Urbana, and is a member of the IEEE, Electrochemical Society, American Vacuum Society and Materials Research Society.

GABE MORETTI, Senior Editor
Gabe Moretti has been in EDA for over 40 years. The first 31 were spent in engineering activities, developing EDA tools and participating in IEEE standards making activities. Now Gabe works as an industry observer, editor, and mentor. In 2007 he received the Ron Waxman Meritorious Service Award from the IEEE. He is the owner of GABEonEDA and was editor of DACeZine.

CAROLINE HAYES, Senior Editor
Caroline Hayes has been a journalist, covering the electronics sector for over 20 years. She has worked on many titles, most recently the pan-European magazine, EPN.

In a previous role, as editor of EPD, she created the e-Legacy Awards and also managed and chaired EPN’s 40th Anniversary Forum at electronica 2012.

DAVE BURSKY, Contributing Editor
Dave is the former Editor-in-Chief of Penton’s Electronic Design and editor at EETimes.

HAMILTON CARTER, Contributing Editor
Hamilton Carter is the Chief Consultant at Pythagorean Productions. He has formerly worked as an engineer at Toshiba and Cadence Design Systems. Hamilton graduated from Ohio State University.

CHRIS CIUFO, Content Director
Chris is Content Director for embedded content for EE Catalog and Embedded Intel® Solutions, covering the print versions, digital channels and newsletters, associated blogs and social media outlets. He has 30 years of embedded technology experience with degrees in electrical engineering and materials science.

ANNE FISHER, Managing Editor
Anne’s experience includes being managing editor, Communications Group, at OpenSystems Media, where she had the opportunity to cover a wide range of embedded solutions in the PICMG ecosystem as well as other technologies.

Editorial Board
Cheryl Ajluni, Consultant, Custom Media Solutions
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Kathryn Kranen, CEO, Jasper Design Automation
Tom Moxon, Consultant, Moxon Design
Scott Sandler, CEO, Novas Software
Steve Schulz, President, Si2
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Integrated 2015 Editorial Calendar

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**Fall Issue:**
- Hardware/Software Integration: Hardware/Software Tradeoffs, IP selection, Optimizing system architecture, Power optimization, PPA
- From Gates to Silicon: Working with Foundries, IP, power/timing analysis, color-aware P&R, 10 & 16 nm and FinFET, Working with Packaging Houses, Prototyping, RTL to GDSII
- Embedded Memories: flash, DRAM, power management, packaging, system optimization
- The Internet of Things: communication protocols, wearables, power, automotive, security, smart homes, smart cities, cloud computing
- IP: libraries, verification, integration, working with foundries, 3D, TVS
- Analog: system integration, 3D, power analysis and distribution, SPICE, Verilog and VHDL, sensors, MEMS
- Devices: Logic, MEMS, Embedded Flash, Analog/mixed-signal, Image Sensing, embedded DRAM, High Voltage, BCD-Power, RF/microwave, Ultra-low power
- EDA: Synthesis, routing, models, debug, compilation, verification, validation, layout, extraction, DRC
- Manufacturing: DFM/DFY/DFT/DFR, 3D Integration, TSVs, Color-aware EDA, Multi-patterning, FinFETs, 28/20/16/10 nm technology, packaging, vertical NAND, memories

**Winter Issue:**
- semiconductor HW-SW CoDesign
- DesignCon 2016 (Santa Clara, CA) Embedded World DATE Industry Buyers’ Guide
- Dec. 7, 14 Dec. 9

Subject to change
System architect, design and test engineers and engineering managers working on advanced SoC designs—Chip Design readers—account for a third of all design engineers. These key enablers influence the purchase of nearly 80% of the total EDA market—or about $4 billion.

**CIRCULATION BY JOB RESPONSIBILITY**

- **Engineering** 53.4%
- **Engineering Management** 27.9%
- **Executive & Other Management** 13.3%
- **Other (R&D etc.)** 5.4%

**Chip/SoC Engineers**
- High-performance IC design 10% or 35,000 engineers
- Mainstream Users Smaller ASICs and FPGA 25% or 87,500 engineers
- Late Adopters PCB and small FPGA 27,500 engineers

**Purchasing Influences**
- Chip/SoC Engineers $150k/person/year
- Mainstream Users $50k/engineer/year
- Late Adopters $10k/engineer very low replacement cycles

**Top 30 Subscribing Companies**
- Altera
- AMD
- Analog Devices
- Atmel
- Broadcom
- Cypress Semiconductor
- Cisco
- Freescale
- Fujitsu
- GLOBALFOUNDRIES
- IBM
- Infineon
- Intel
- Hewlett-Packard
- LSI
- Marvell
- Maxim Integrated
- NVIDIA
- NXP Semiconductors
- ON Semiconductor
- Oracle
- PMC-Sierra
- Qualcomm
- GLOBALFOUNDRIES
- Rohm Semiconductor
- Samsung Electronics
- ST Microelectronics
- Texas Instruments
- VIA Technologies
- Xilinx

**Circulation breakdown by Purchasing Responsibility**

<table>
<thead>
<tr>
<th>Category</th>
<th>Percentage</th>
</tr>
</thead>
<tbody>
<tr>
<td>Specify/Authorize/Influence the purchase of Design Automation tools and software</td>
<td>94.8%</td>
</tr>
<tr>
<td>Specify/Authorize/Influence the purchase of ASICs, FPGAs and PLDs</td>
<td>80.6%</td>
</tr>
<tr>
<td>Specify/Authorize/Influence the purchase of Intellectual Property</td>
<td>70.1%</td>
</tr>
<tr>
<td>Specify/Authorize/Influence the purchase of Test Equipment/Development Tools</td>
<td>52.9%</td>
</tr>
<tr>
<td>Influence, specify or authorize the purchasing at companies with revenues of over $500 million.</td>
<td>57.2%</td>
</tr>
<tr>
<td></td>
<td>35.6%</td>
</tr>
</tbody>
</table>

Click here for sales contact information.
Magazine: Advertising

Increase consideration and preference for your products among the most qualified decision makers

Chip Design Magazine is the only global publication serving design engineers and engineering managers working on advanced SoC designs.

- Circulation: 40,000 qualified subscribers plus trade show distribution (see Editorial Calendar on page 4)
- Purchasing influence: 100% of subscribers influence purchasing decisions for EDA tools & services; ASICS, FPGAs and PLDs; Intellectual Property or Test equipment/development tools (see Audience Demographics on page 6)
- Frequency: 4 issues per year

SPONSOR BENEFITS:

Brand Awareness
Increase consideration and preference for your company and products by aligning your message with our authoritative content.

Thought leadership
Positions your company as a knowledge leader to an active and engaged audience of decision makers, helping to build business through advocacy and referral.

Traffic Driver
Prominent links and QR codes in your ad push decision makers directly to your website or sales team to increase purchase intention and activity.

Product Marketing
Showcase your key products and services. Align your product with important ecosystems servicing the Industry.

MAGAZINE ADVERTISING NET RATES (includes 4-color, 15% agency discount):

<table>
<thead>
<tr>
<th>Display Advertising/ Advertorials</th>
<th>1x</th>
<th>2x</th>
<th>4x</th>
</tr>
</thead>
<tbody>
<tr>
<td>Two-page Spread</td>
<td>$5,000</td>
<td>$4,000</td>
<td>$2,900</td>
</tr>
<tr>
<td>Full Page</td>
<td>$3,500</td>
<td>$2,750</td>
<td>$2,000</td>
</tr>
<tr>
<td>Half Page</td>
<td>$2,500</td>
<td>$2,000</td>
<td>$1,500</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Premium Option</th>
<th>Standard Rate</th>
</tr>
</thead>
<tbody>
<tr>
<td>Back Cover</td>
<td>$5,000</td>
</tr>
<tr>
<td>Inside Back Cover</td>
<td>$4,000</td>
</tr>
<tr>
<td>Inside Front Cover Spread</td>
<td>$4,000</td>
</tr>
</tbody>
</table>

83% of respondents are more likely to click on an online ad if they have seen that company’s ad in an industry magazine.

Source: Advertising Engagement Study
Product Showcase

Put your sales message where buyers are looking for products

Promoting your products in the Showcase section of Chip Design magazine is a great way to generate interest and drive prospects to your website, literature, products and services—both new and established. Your message will reach 40,000 design engineers and engineering managers working in advanced SoC designs who subscribe to Chip Design magazine plus our website visitors who will see it in online in the Featured Solutions Center, including a link to your company’s website!

Your product will also be featured with a link to your company’s website in four issues of Chip Designer email newsletter – a total reach of over 160,000!

No time for new creative? We’ll produce the ad for you and supply a proof at no extra charge.

ADVERTISER BENEFITS:

Brand Awareness: Your product is visible to decision makers who have affinity for the Chip Design content, helping to increase consideration and preference.

Traffic Driver: Pushes decision makers to your website to learn more about your company and products, to help increase purchase intention and activity.

SPECIFICATIONS:

1 Page Product Showcase
• 1500 characters + additional text (varies per catalog, see online form)
• 3 9/16” (300 dpi) wide (height determined by fit on page)
• approx. 1.5” x 1.5” (exact size determined by fit on page)

1/2 Page Product Showcase
• 700 characters + additional text (varies per catalog, see online form)
• approx. 1.5” x 1.5” (exact size determined by fit on page)

Content for datasheets is submitted via an online form only. Contact our production staff if you do not know the location of a particular submission form.

2014 NET RATES

Full Page Product Showcase
$1,500
(additional products 50% off)
1/2 page Product Showcase
Net Rate: $1,000
(additional products 35% off)

Full Page Product Showcase + Featured in Dedicated Email Blast + 40,000 subscribers
Net Rate: $2,950

Please contact
Jenna Johnson at jjohnson@extensionmedia.com

Click here for sales contact information.
Trade Show Programs

DAC Packages
Chip Design Trade Show Packages give your company **increased exposure at the industry’s main events.**

**MAGAZINE INCENTIVES**
Digital display advertisers in the DAC pre-show and show issues receive:
- **Resource Guide Product Showcase FREE in the show issue**

**VIDEO SHOWCASE PROGRAM**
- Promote a new product or announcement on camera at DAC
- Your video will be recorded at the event then posted on the Chip Design website and promoted in eight issues of Chip Designer to more than 40,000 SoC Designer decision makers
- PLUS, you receive a copy of the video to post on your site or YouTube and use for other marketing efforts
- Net rate $2,000; $2,500 for editorial interview

**PRODUCT SHOWCASE SPECIFICATIONS:**
- 150x150 image
- 50 words of text including your booth number
- URL link

**BANNER ADS IN NEWSLETTER:**
- Leaderboard (468 x 60) - $1,500 net
- Skyscraper (120 x 600) on right rail - $1,500 net
- Silver (125x125) on right rail - $750 net (limited availability)

**E-SHOW DAILY**
Leverage Chip Design's DAC coverage by positioning your advertising in our special e-Show Daily e-Newsletter and on ChipDesignMag.com distributed daily during DAC (June 8-10). The daily newsletter goes out to over 35,000 subscribers.

**E-SHOW DAILY CREATIVE SPECIFICATIONS:**
- Banners: 35k max. file size, .gif or .jpg (no animated .gifs or flash)

**E-SHOW DAILY NET RATES**

<table>
<thead>
<tr>
<th>Position</th>
<th>Size</th>
<th>Net Rate</th>
</tr>
</thead>
<tbody>
<tr>
<td>Platinum</td>
<td>468 x 60 + 1st text ad</td>
<td>$3,000</td>
</tr>
<tr>
<td>Gold</td>
<td>120 x 600 + 2nd text ad</td>
<td>$2,500</td>
</tr>
<tr>
<td>Silver #1</td>
<td>125 x 125 + 3rd text ad</td>
<td>$1,500</td>
</tr>
<tr>
<td>Silver #2</td>
<td>125 x 125 + 4th text ad</td>
<td>$1,500</td>
</tr>
<tr>
<td>Silver #3</td>
<td>125 x 125 + 5th text ad</td>
<td>$1,500</td>
</tr>
</tbody>
</table>

* Includes insertion in all three e-Newsletters delivered during selected show
* Bonus Distribution Issue
Gateway Sponsorships & Online: Chip Design Banners

Influence decision makers when they are online


The Chip Design website offers Welcome Page and Homepage banners that generate **broad visibility for your brand and product messaging** among design engineers and engineering managers working on advanced SoC designs worldwide. Prominent banner positions align your message with our respected editorial content serving the information needs of these influential decision makers.

The **Welcome Page** banner offers ultimate brand visibility for a major announcement or introduction. Your large 800x600 ad unit is seen by every visitor to the Chip Design portal homepage and article pages. Each visitor to these pages sees your message a maximum of once per day. The Welcome Page is our largest available advertising unit and is exclusive to one advertiser per week.

**HIGH IMPACT GATEWAY SPONSORSHIP**

- Logo branding as Market Leader sponsor on website
- 20,000 leaderboard or large rectangle banners Impressions per month on www.ChipDesignMag.com
- Platinum sponsor of one issue of Chip Designer per month
- One dedicated email blast per quarter to 10,000
- Unlimited Product Announcements

**3-MONTH SPONSOR NET RATE:** $9,000 ($13,500 with dedicated email blast to 45,000 newsletter subscribers)

**ADVERTISER BENEFITS:**

**Brand Awareness:** Strengthens your company’s visibility with prominent advertising on a site that is trusted by decision makers for electronics manufacturing to increase consideration and preference.

**Traffic Driver:** Pushes users to your website or other online offerings to learn more and increase purchase intention and activity.

**CHIPDESIGNMAG.COM WEBSITE MARKETING NET RATES:**

**“Spotlight On” Position (limited to 2 companies)**

High impact and above the fold, this position leverages your headlines to drive maximum visibility and traffic to your site

Price - $4,000 per month

**Expandable Banner Showcase**

High impact, center column position showcases your company as a market leader

Price - $2,950 per month (limited to 2 companies)

**Banners**

- Leaderboard (728x90) - $100 cpm
- Large Rectangle (336x280) - $100 cpm
- Half Page (300x600) - $100 cpm
- Welcome Page (800x600) - $450 cpm
- Standard Pop-Under (336x280) - $350 cpm appears when browser closes

**PR Maximizer (New)**

Unlimited PR; rotating 125x125 banner

Price: $850 or $95 per month (6 month minimum; automatic renewal)

Add on: One Print Product Showcase ($1,500 total)

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**CHIPDESIGNMAG.COM PORTAL QUICK FACTS:**

Avg. Monthly Page Views: 237,598
Page Visits: 42,053
Avg.Time on Site: 48:31

Click here for sales contact information.
Newsletter Sponsorships

Reach targeted Audiences with Chip Design Email Newsletters

**CHIP DESIGNER E-NEWSLETTER (BI-MONTHLY)**
SoC digital and analog designers, system architects, IP integrators, DFM and verification engineers benefit from the latest news, viewpoints and technical articles. Covers such topics as ESL, IP, analog mixed signal, power, DFM-DFY, nanotechnology and more.

**IP DESIGNER - INTEGRATOR E-NEWSLETTER (MONTHLY)**
Intellectual Property (IP) design and integration remains one of the hottest trends in the chip industry. Coverage includes trends in analog-digital, core-memory, design, verification, integration and qualification of IP in the SoC space.

**RF & MICROWAVE SYSTEMS E-NEWSLETTER (QUARTERLY)**
Trends, viewpoints, news and technical articles for design engineers and managers developing advanced RF and Microwave Systems designs

**FPGA & CPLD QUARTERLY UPDATE E-NEWSLETTER**
News and product solutions for FPGA and PLD system application engineers.

**ADVERTISER BENEFITS:**

**Brand Awareness:** Provide broad visibility for your message and products, while aligning them with timely editorial content to increase consideration and preference.

**Traffic Driver:** Push decision makers to your website to learn more and increase purchase intention and activity.

**OPTIONS (NET RATES)**

**Exclusive Roadblock - Limited to one Sponsor**
468x60 banner at top center position; side banner 125 x up to 728; up to three text ads;
- $5,000/issue

**Platinum Sponsor - Exclusive**
468x90 banner at top center position and first text ad
- $2,000/issue

**Gold Sponsor - Exclusive**
Skyscraper top right banner position and second text ad
- $1,500/issue

**Silver Sponsor - Exclusive**
Second/third from top 125 x 125 banner position and third/fourth text ad
- $1,000/issue
Lead Generation: Technology Paper Sponsorship

Generate leads as a thought leader in Chip Design

Publish your paper and demonstrate your company’s thought leadership on www.chipdesignmag.com and in the leading magazine serving design engineers and engineering managers working on advanced SoC designs. This sponsorship also allows you to generate leads to more easily quantify the return on your investment. And no magazine creative is required. We’ll produce the creative and supply a proof at no charge.

SPONSOR BENEFITS:

Brand Awareness
Increase consideration and preference for your company and products among electronics manufacturing professionals by aligning your authoritative content with ours.

Lead Generation
Publish your paper abstract in Chip Design magazine with a link to the full paper in our online technical paper library to attract targeted leads, and increase purchase intention and activity.

Thought Leadership
Position your company as a knowledge leader to an active and engaged audience of decision makers, helping to build business through advocacy and referral.

SPONSORSHIP INCLUDES:

• Full-page synopsis of paper with sponsor name and contact information at the end along with a link to the full paper, which is posted on the Chip Design site for six months as a PDF. The synopsis can include two images, up to 250 words and a short title.
• Landing page on Chip Design site where visitors download the full paper—including sponsor logo, which links to your website, plus paper title and description.
• Registration form (optional) to collect downloaders’ contact information.
• Featured in six issues of Chip Designer e-Newsletter.
• All paper submissions are subject to review and approval by our editorial staff.

SPONSORSHIP NET RATE:

• $2,500 (includes online and magazine)
• $3,995 (includes online, magazine, and dedicated email blast to 20,000)
• $1,500 (online only)
Lead Generation:  
Market Surveys and Dedicated Emails

Gain valuable market intelligence and generate leads with detailed demographics

Each quarter in 2015, Chip Design will conduct a Market Intelligence Survey of its readership. Data collected includes industry trends, buying preferences, key factors influencing purchasing and evaluation decisions and much more including contact data on all respondents.

2014 MARKET INTELLIGENCE/LEAD GENERATION TOPICS | PARTICIPATION DEADLINES:

- EDA Tech & Tools — February
- RF/Microwave — April
- ASIC Prototyping — June
- Verification — September
- 10nm Readiness— October

SPONSOR BENEFITS INCLUDE:

- Participation in creating survey questions
- Executive summary and analysis
- All research data
- All contact data with detailed demographics - LEADS!

SPONSORSHIP NET RATE:

$5,000 (sponsor may add up to 3 proprietary questions at an additional fee of $2,500 per program)

Sign-up for all 4 surveys for $15,000

Custom Research and Lead Generation Program

Gain valuable intelligence and leads based on a topic you choose. Sponsors provides up tp 15 questions. We provide a 4-page executive summary, and contact information on all survey respondents. 200 guaranteed responses/leads.

Sponsorship net rate: $9,500

Please contact your sales representative for pricing and further information.
Editorial Sponsorships: Systems Design Engineering
Premium content channel

Creating valuable content featuring your company and technology...
System Engineering Design was created by Chip architects, engineers and journalists to help simplify the increasingly complex task of designing and developing new semiconductors. It consists of a monthly newsletter, daily updates, videos, research, webcasts and a website.

Delivering it to your target audience

CONTENT

THE REACH

 Featured in Chip Design Magazine
41,000 subscribers

Featured in the monthly System Engineering Design newsletters
60,157 subscribers

Chip Design Facebook + LinkedIn
Highlighted on 2 different related LinkedIn Groups (over 40,100 members)

Effective Email Newsletter Distribution
34,896 subscribers

Influencing through SOCIAL MEDIA

SPONSORSHIP INCLUDES:
• Participation in monthly roundtable discussions on technical subjects
• Exclusive opportunity to contribute white papers about technical issues
• Participation in CTO/CEO interviews
• Exclusive right to suggest content and coverage areas
• Exclusive opportunity to contribute blogs on technical subjects
• Prominent links to your website
• Sponsor events will be listed first on the website calendar
• Sponsors will have right of first refusal for all multimedia interviews

SPONSORSHIP NET RATE:
Platinum Level: (top logo positions; and each month featured in 2 articles and 1 deeper dive news story, 1 featured blog position, and coverage in multiple news and blog roundups and videos)
- $5,500 per month (6 month minimum).

Gold Level: (Logo sponsor branding; and each month featured in 1 article, 1 featured blog position and coverage in the news and blog roundups and videos) - $3,500 per month (6 month minimum)
Video Sponsorships

Drive more targeted viewership and leads for your video content

Video is an ideal medium for showcasing and demonstrating new products, creating visibility for senior executives and technology experts, and extending the life of your face-to-face event presentations to reach a much larger audience after the show, including those who didn’t visit your booth. ChipDesignMag.com has the SEO expertise and content depth to ensure greater visibility for your video content among a more targeted audience than any other sites can offer.

SPONSOR BENEFITS:

Brand Awareness:
Position your company as a market leader to an engaged audience of manufacturing professionals involved in purchasing products.

Thought Leadership/Education:
Educate customers and prospects with your unique industry and product knowledge, and elevate the perception of your brand.

VIDEO SHOWCASE PROGRAM

• Promote a new product or announcement on camera at DesignCon, DVCon, or DAC
• Your video will be recorded at the event then posted on the Chip Design website and promoted in 8 Chip Designers e-Newsletter issues reaching a combined list more than 40,000 manufacturing decision makers
• PLUS, you receive a copy of the video to post on your site or YouTube and use for other marketing efforts

NET RATE: $2,000; $2,500 for editorial interview

Already have your own videos? Take advantage of our traffic and exposure to a targeted audience by having them hosted on Solid-State.com.

<table>
<thead>
<tr>
<th>Sponsorship</th>
<th>Specifications</th>
<th>Net Rate</th>
</tr>
</thead>
<tbody>
<tr>
<td>Video Sponsorship</td>
<td>• Recommended video clip length: 3 to 5 minutes 480 x 360 pixels (4:3), 480 x 270 pixels (16:9) Recommended formats: .mpeg4, .mov Acceptable formats: .wmv, .avi, .mpeg2, .flv, 3gp, .dv, h.264 125 x 125 + 5rd text ad</td>
<td>$1,500 per video (3-month sponsorship)</td>
</tr>
</tbody>
</table>

Click here for sales contact information.
CoNtENt MarkETiNg toolS:

Deliver valuable, relevant and compelling content to your customers on a constant basis

CONTENT MARKETING TOOLS:

- Blogs
- Articles
- Case Studies
- White Papers
- eNewsletters
- Digital Magazine
- Editorial Videos
- eBook
- Social Media Delivery

PRICING:

Hire Chip Design editorial and marketing teams to create content that engages your customers and prospects and effectively tells your value proposition.

- Monthly Blog (250 words) - $1,500 per month (6 month minimum)
- Article (3 pages) (1,200 to 1,500 words max) - $5,000
- Case Study (4 pages) (1,800 words max) - $7,500
- White paper (10 pages) - $12,500
- eNewsletter - Quoted upon request
- Digital Magazine - Quoted upon request

Leverage Chip Design network of websites, magazines and email newsletters to reach targeted technology purchasers.

- Editorial video (up to 5 minutes) - $2,500
- eBook - Quoted upon request
- Monthly content delivery service (3 articles/videos/blogs per month) - Quoted upon request
- Social Media Enhancement - Quoted upon request
- Print magazine/Newsletter - Quoted upon request
Focus on FPGAs and PLDs

Target over 165,000 FPLD and PLD system and application engineers

EECatalog.com provides direct access to the FPGA and PLD community, connecting more than 165,000 readers annually with the newest, most innovative solutions from market leaders world-wide!

Our experienced editorial team delivers high-value editorial content for a senior engineering audience covering: Industry Trends, viewpoints, News, Case Studies, Technical articles, Blogs & videos

Subscriber Profile: Qualified FPGA and PLD system and application engineers and managers.

Why utilize this influential industry platform? 98.1% of our readers specify, authorize and influence the purchase of FPGA and PLD solutions.

How does Chip Design & Embedded Systems Engineering reach this target audience?

Annual Engineers’ Guide: Distributed to 35,000+ direct requests and qualified FPGA and PLD system and application engineers and managers - with an average pass-a-long readership of 1.5 per copy, that’s a reach of 57,500!

Events distribution of the Engineers’ Guide at key industry events:
- DesignCon (Santa Clara: January)
- Embedded World (Nuremberg: February)
- DAC (San Francisco: June)
- Embedded Systems Conference (Silicon Valley)

FPGA and PLD Email Newsletter: 4 quarterly issues showcasing products and services sent to 37,134 developers and engineers who influence the purchase of hardware, software, and services.

Online: aggressively promoted with major search engine advertising at www.eecatalog.com/fpga

OPTIONS:

Channel Sponsorship
Reinforce you market lender position in this market.
12 month channel sponsorships are available for between $8,000 to $18,000. Ask sales rep for details

Website Marketing
Banners - $125 cpm
Spotlight on Exclusive Position - $2,000 per month

Email Newsletter Sponsorships
Platinum Sponsor - $1,500
Gold Sponsor - $950

Engineers’ Guide
Full page Product Showcase (Print, digital, online, newsletters) - $1,250
Display Ads/Advertorials - $2,000 to $4,000 (depending of position)

Direct Response
Dedicated Email Blasts - $300 cpm (15,000 minimum)
White Paper Lead Generator - $1,500 per white paper

FPGA and PLD QUICK FACTS:

- Newsletter Subscribers: 37,134
- Average Monthly Page Views: 25,000+
- Average Monthly Unique Visitors: 6,983

Click here for sales contact information.
Focus on RF and Microwave Systems

Reach 120,000+ engineers and executive managers actively engaged in modeling, design, and test of RF and microwave SoCs!

**RF and Microwave Systems** provides direct access to the RF and Microwave Systems community, connecting more than 147,000 readers annually with the newest, most innovative solutions from market leaders world-wide!

Our experienced editorial team delivers high-value editorial content for a senior engineering audience covering: Industry Trends, viewpoints, News, Case Studies, Technical articles, Blogs & videos

**Subscriber Profile:** Analog and digital IC engineers, system engineers and executive managers actively engaged in the high-frequency modeling, design, verification, and test of RF and microwave System-on-Chips (SoCs).

**Why utilize this influential industry platform?** 97.4% of our readers specify, authorize and influence the purchase of RF and Microwave ICs, software, test, tools, and services.

**How does RF and Microwave Systems reach this target audience?**

**Annual Print/Digital Publication:** Distributed to 35,000 direct requests and qualified managers actively engaged in modeling, design, and test of RF and microwave SoCs - with an average pass-a-long readership of 1.5 per copy, that’s a reach of 52,500!

**Events distribution of the Engineers’ Guide at key industry events:**
- IMS (Tampa Bay, FL)
- DAC (San Francisco, CA)
- Mobile World Congress (Barcelona)
- Embedded World (Nuremberg)

**Online:** aggressively promoted with major search engine advertising at www.chipdesignmag.com/rfmw

**RF and Microwave Systems Email Newsletter:** 4 quarterly issues showcasing products and services sent to 32,428 developers and engineers who influence the purchase of hardware, software, and services.

**OPTIONS:**

**Channel Sponsorship**
Reinforce your market leader position in this market.
12 month channel sponsorships are available for between $6,000 to $15,000.
Ask sales rep for details

**Website Marketing**
Banners - $100 cpm | Spotlight on Exclusive Position - $ 2,000 per month

**Email Newsletter Sponsorships**
Platinum Sponsor - $1,500 | Gold Sponsor - $950

**Product Showcase**
Full page Product Showcase (Print, digital, online, newsletters) - $1,250
Display Ads/ Advertorials - $2,000 to $4,000 (depending on position)

**Direct Response**
Dedicated Email Blasts - $300 cpm (15,000 minimum)
White Paper Lead Generator - $1,500 per white paper
Focus on **Sensors and MEMS**

Reach 124,000+ developers and engineers using embedded sensors, MEMS, and signal technologies!

**Chip Design & EECatalog** provides direct access to the sensors & MEMS community, connecting more than 124,000 readers annually with the newest, most innovative solutions from market leaders world-wide!

Our experienced editorial team delivers high-value editorial content for a senior engineering audience covering: Industry Trends, Viewpoints, News, Case Studies, Technical articles, Blogs & videos

**Audience Profile:** Architects, designers, engineers and managers working with MEMS tools, embedded sensors and RF/wireless, analog, signal conditioning, power conversion and data acquisition technologies. 98.1% of our readers specify, authorize and influence the purchase of embedded sensors and MEMS technologies.

**How does Chip Design and Embedded Systems Engineering reach this target audience?**

**Annual Print/Digital Engineers’ Guide:** distributed to 40,000 direct requests and qualified developers, engineers and managers using embedded sensors, MEMS, and signal technologies—with an average pass-a-long readership of 1.5 per copy, that’s a reach of 60,000!

**Events distribution of the Engineers’ Guide at key industry events:**
- Sensors Expo & Conference (Rosemont, IL)
- SEMICON West (San Francisco)
- Embedded World (Nuremberg)
- Embedded Systems Conference Silicon Valley (Santa Clara)

**Sensors & MEMS Email Newsletter:** 4 quarterly issues showcasing products and services sent to 27,948 developers and engineers who influence the purchase of hardware, software, and services.

**Online:** aggressively promoted with major search engine advertising at [www.eecatalog.com/sensors](http://www.eecatalog.com/sensors)

**OPTIONS:**

**Channel Sponsorship**
Reinforce your market leader position in this market.
12 month channel sponsorships are available for between $6,000 to $15,000.
Ask sales rep for details

**Website Marketing**
- Banners - $125 cpm
- Spotlight on Exclusive Position - $2,000 per month

**Email Newsletter Sponsorships**
- Platinum Sponsor - $1,500
- Gold Sponsor - $950

**Engineers’ Guide**
Full page Product Showcase (Print, digital, online, newsletters) - $1,250
Display Ads/ Advertorials - $2,000 to $4,000 (depending of position)

**Direct Response**
- Dedicated Email Blasts - $300 cpm (15,000 minimum)
- White Paper Lead Generator - $1,500 per white paper

**SENSORS & MEMS CHANNEL QUICK FACTS:**
- Newsletter Subscribers: 27,948
- Average Monthly Page Views: 20,000+
- Average Monthly Unique Visitors: 6,568

Click here for sales contact information.
Reach 200,000+ developers and engineers using multicore & virtualization technologies!

Chip Design and EECatalog.com provides direct access to the multicore & virtualization community, connecting more than 200,000 readers annually with the newest, most innovative solutions from market leaders world-wide!

Our experienced editorial team delivers high-value editorial content for a senior engineering audience covering: Industry Trends, viewpoints, News, Case Studies, Technical articles, Blogs & videos

Audience Profile: Developers, Engineers and Managers using multicore and virtualization technologies. 98.5% of our readers specify, authorize and influence the purchase of multicore and virtualization technologies.

How does Chip Design and Embedded Systems Engineering reach this target audience?

Annual Print/Digital Engineers’ Guide: distributed to 45,000 direct requests and qualified developers, engineers and managers using multicore and virtualization technologies—with an average pass-a-long readership of 1.5 per copy, that’s a reach of 67,500!

Events distribution of the Engineers’ Guide at key industry events:

- Multicore Developers Conference
- DAC

Multicore & Virtualization Email Newsletter: 4 quarterly issues showcasing products and services sent to developers and engineers who influence the purchase of hardware, software, and services.

Online: aggressively promoted with major search engine advertising at www.eecatalog.com/multicore

OPTIONS:

Channel Sponsorship
Reinforce you market lender position in this market. 12 month channel sponsorships are available for between $6,000 to $15,000. Ask sales rep for details

Website Marketing
Banners - $130 cpm
Spotlight on Exclusive Position - $ 2,000 per month

Email Newsletter Sponsorships
Platinum Sponsor - $1,500
Gold Sponsor - $950

Engineers’ Guide
Full page Product Showcase (Print, digital, online, newsletters) - $1,250
Display Ads/ Advertorials - $2,000 to $4,000 (depending of position)

Direct Response
Dedicated Email Blasts - $300 cpm (15,000 minimum)
White Paper Lead Generator - $1,500 per white paper

MULTICORE CHANNEL
QUICK FACTS:

Newsletter Subscribers: 44,042
Average Monthly Page Views: 30,000+
Average Monthly Unique Visitors: 7,133

Click here for sales contact information.
The Multicore Developers Conference
May 6 - 7, 2015 Hyatt Regency, Santa Clara

MULTICORE DEVCON FOCUS
The excitement surrounding multicore technology continues to grow as more and more companies come on board, but product developers and designers continue to face serious development opportunities and challenges. The Multicore DevCon brings together engineers and executives to participate in a forum dedicated to multicore technology and learn about products and tools from a practical perspective. Multicore DevCon is not just about multicore, but also many other related technologies including virtualization, many-core, development/debug tools and application-specific topics including networking, android, military and aerospace.

Why Participate in the Multicore DevCon?

• The Multicore DevCon is a 2-day, stand-alone event 100% dedicated to developers, designers, engineers, and executives using multicore and virtualization technologies and providing attendees, sponsors and exhibitors with a venue that encourages networking and productive discussions.
• All qualified attendees will be admitted at no cost to Multicore DevCon.
• Multicore DevCon leverages the Chip Design and EECatalog Network to deliver an exceptional conference venue and a focused marketing program designed to reach your potential customer base year-round including the Multicore and Virtualization Monthly Update (email newsletter broadcast to 44,000+ subscribers), a dedicated website (www.eecatalog.com/multicore), email blasts, and the Engineers’ Guide to Multicore and Virtualization/Multicore DevCon show guide.
• 721 qualified attendees registered for the 2013 Multicore Developers Conference. Based on the overwhelming positive response we received we expect an even greater response in 2015.

To learn more about how your company can participate in Multicore DevCon, contact Clair Bright at cbright@extensionmedia.com.
The Internet of Things Developers Conference
May 6 - 7, 2015 Hyatt Regency, Santa Clara

TWO FULL DAYS OF KEYNOTES, TRAINING SESSIONS AND PANEL DISCUSSIONS. TOPICS COVERED INCLUDE:

- Security
- Adopting legacy industrial connectivity solutions
- Communication gateways
- Differentiating Greenfield and Brownfield
- Embedded cloud computing
- Semiconductor technologies of the future for IoT
- Making money with the Internet of Things
- Networking, LTE equipment, and Femtocells
- Utilizing ultra-low power microcontrollers in IoT devices
- Software development environments for IoT and M2M applications

Over 1,200 Pre-qualified attendees to the 2014 Internet of Things Developers Conference

TARGETED IoT AUDIENCE & READERSHIP

Breakdown by Purchasing Responsibility

Purchasing Authority or Influence:
96.8% YES / 3.2% NO

Authorize or Influence Purchase of IC’s and Semiconductors
90.6%

Authorize or Influence Purchase of System Boards
83.9%

Authorize or Influence Purchase of Software
92.4%

36.9% Design Engineering
18.4% Engineering Management
12.9% Embedded Developers
11.4% Systems Architects
11.1% Executive Management
5.2% Other
4.1% Systems Integrators

To learn more about how your company can participate in Multicore DevCon, contact Clair Bright at cbright@extensionmedia.com.
The Confab

The 11th Annual ConFab
May 19-22, 2015

ATTENDEE PROFILE
Sponsors of The ConFab gain the unique opportunity to meet with a verified group of influential executives involved in buying the total spectrum of products, materials and services involved in semiconductor manufacturing and design. These executives have historically represented the world’s top OEMs, fabless/design companies, fabs and foundries from the United States, Europe, China, Taiwan, Japan and Korea.

ATTENDEE JOB TITLES INCLUDE:
- CEO
- Vice President of Operations
- Director of Manufacturing
- Director of Facilities
- Technical and Packaging Developer
- CTO
- Vice President of Manufacturing
- Director of Operations
- Director of External Wafer Packaging
- Fab Manager

PREVIOUS ATTENDEES INCLUDE:
- Advanced Semiconductor Manufacturing Corp. (ASMC)
- Amkor Technology
- ASE Inc.
- CSMC Technologies Corp.
- Freescale Semiconductor
- GLOBALFOUNDRIES
- Hattori Consulting International
- Hitec Semiconductor (Wuxi) Co.
- IBM Corp.
- Infineon Technologies Dresden GmbH
- Intel Corp.
- International Rectifier
- LSI Corp.
- MEMSCAP, Inc.
- Nvidia Corp.
- ON Semiconductor Corp.
- ON Semiconductor Philippines, Inc.
- Qualcomm Inc.
- Renesas Electronics America
- Semiconductor Manufacturing International Corp. (SMIC)
- Shanghai Belling Co.
- Shanghai Hua Hong NEC Electronics Co.
- TSMC
- VIA Technologies, Inc
- X-FAB Texas, Inc.
- Xilinx, Inc.

To learn more about how your company can participate in The ConFab, contact Sales Manager Sabrina Straub at 603-770-6569 or sstraub@extensionmedia.com.

SPONSOR BENEFITS:
The Attendees
The ConFab’s attendees are all pre-screened decision makers who have historically represented the world’s top device manufacturers, OEMs, foundries and fabless companies. These qualifications ensure productive, substantive interactions and maximum ROI for sponsors.

The Networking
Well-attended evening receptions, plus breakfasts, lunches and refreshment breaks offer unparalleled networking opportunities for attendees and sponsors to meet and connect in a relaxed environment conducive to making lasting connections.

The Meetings
At the 2014 ConFab, more than 175 meetings took place during which sponsors and their customers, both prospective and existing, engaged in strategic discussions and created crucial alliances for the future. These pre-scheduled, private boardroom meetings offer an efficient and highly effective approach to conducting face-to-face business in a global industry.

Click here for sales contact information.
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